

DBI® Ultra Die-to-Wafer Hybrid Bonding

The ultimate 2.5D & 3D integration technology for high performance computing

High Bandwidth

High Capacity

Thin Profile

Low Power

Low Cost



Data Centers



AI, Machine Learning &
Deep Learning Hardware



Automotive



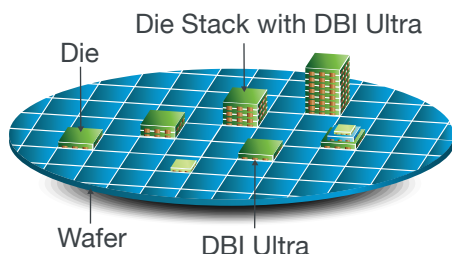
Gaming



Consumer
Electronics



Industrial
& Scientific

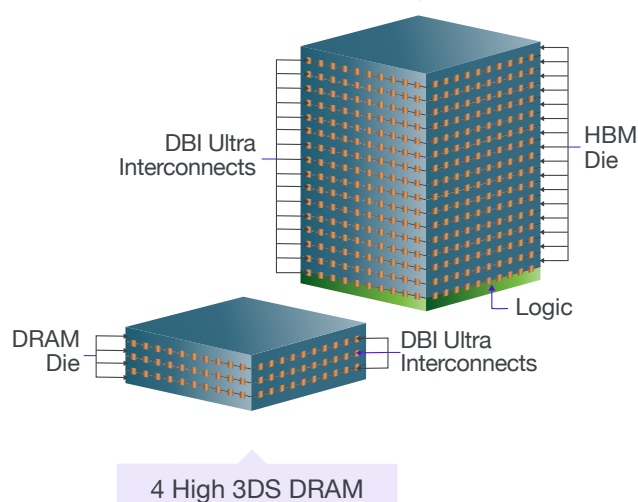


Ultimate Integration Flexibility

Accommodates various die sizes, wafer sizes, process technology nodes, etc.

Enabling 3D Stacked Memory Solutions

4, 8, 12, 16 or more high HBM2, HBM3 & beyond



Enabling Next Generation High Performance Computing

2.5D Integration with DBI Ultra

